

RC Connect-R™



Cost-Effective High-Performance Stamped Contact Technology for Area Array Applications



Highly Consistent Compression Mount Connectors Down to .6mm Pitch

Density & Scalability

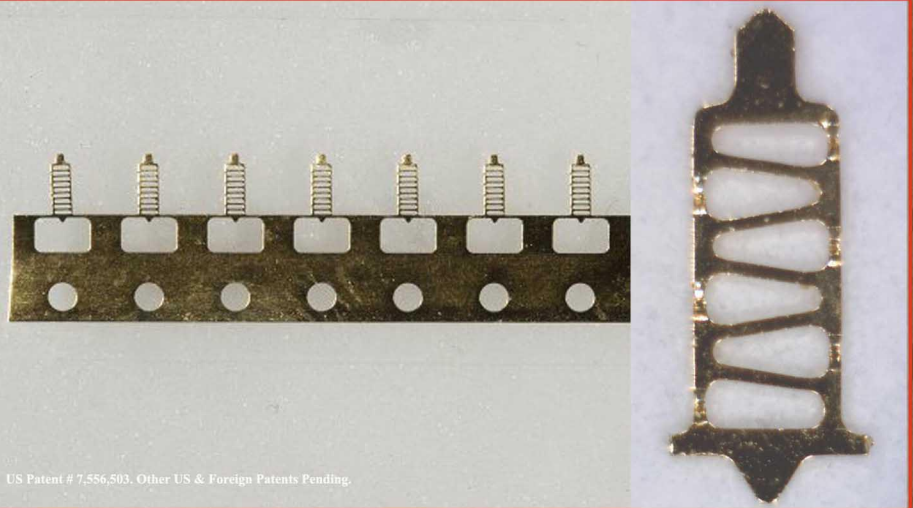
Down to .6mm Pitch in Area Array
As Short as 2.2mm Mated Height
Up to 2K+ Nodes Per Connector

Bandwidth & Electrical Performance

As High as 25 GHz at -1dB
As Low as .82 nH Self-Inductance

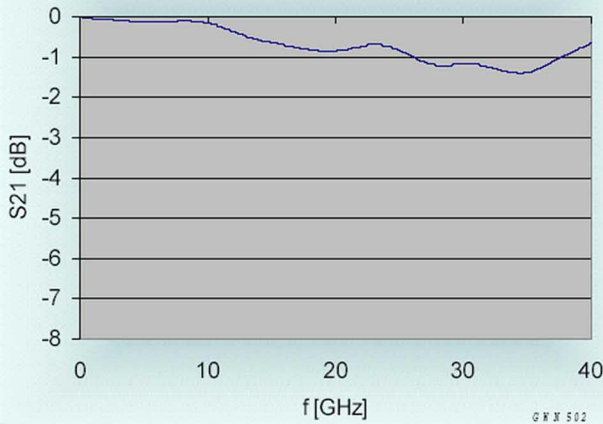
Cost & Simplicity

Revolutionary Stamped Shape
Standard Metallurgy, Materials, Plating
Designed for High Volume Automated Assembly

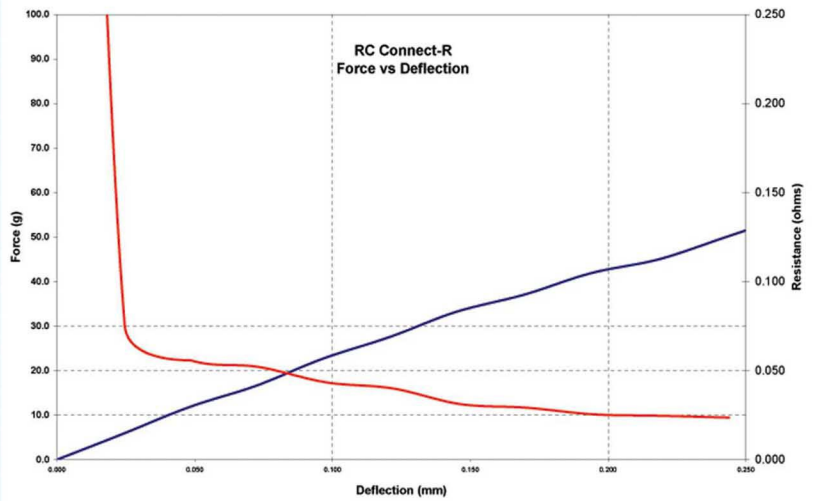


US Patent # 7,556,503. Other US & Foreign Patents Pending.

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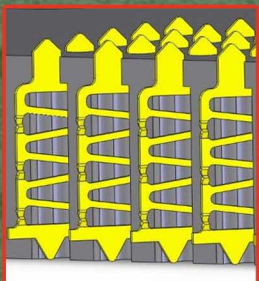
AC Performance at .8mm Pitch



Force vs. Deflection vs. Resistance at .8mm Pitch

Next Generation Stamped Contact Technology for BGA/LGA

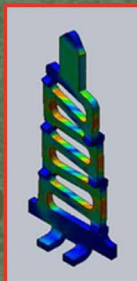
Area Array



USA Dime



Compressed



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15 Degree Lateral
"Scrub" Action At Tip
Penetrates Oxides